

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph at page 37, line 2, with the following rewritten paragraph:

-- Tapes ~~12, 12~~ are attached to a long support film ~~10~~, and the support film ~~10~~ is attached to frame member ~~18~~ at positions where the tape ~~12~~ to be stuck to an adherend, such as a semiconductor wafer, ~~14~~ is included in a frame of ~~the~~ a frame member ~~18~~. The support film ~~10~~ is pressed to stick the tape ~~12~~ to the adherend ~~14~~, and the support film ~~10~~ is released from the tape ~~12~~. The support film ~~10~~ is transferred and the above operations are repeated to stick the tapes ~~12, 12~~ to the respective adherends ~~14, 14~~. ~~The~~ In this manner, the tension to the tape 12 is diffused to the support film 10, and the frame member 18 blocks causes the tension of the support film 10 to reside outside of the frame. Accordingly, the tape 12 stuck to the adherend 14 has reduced residual stress and the adherend such as a thin semiconductor wafer to which the tape has been stuck can be prevented is free from warpage which would otherwise be caused by a tape applied under tension. --